

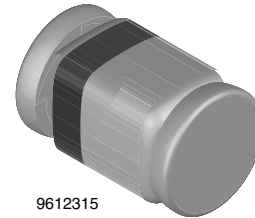
Small Signal Schottky Diode

Features

- Integrated protection ring against static discharge
- Very low forward voltage
- AEC-Q101 qualified
- Compliant to RoHS directive 2002/95/EC and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21 definition



RoHS
COMPLIANT
HALOGEN
FREE



9612315

Applications

- Applications where a very low forward voltage is required

Mechanical Data

Case: MicroMELF

Weight: approx. 12 mg

Cathode band color: black

Packaging codes/options:

TR3/10 k per 13" reel (8 mm tape), 10 k/box

TR/2.5 k per 7" reel (8 mm tape), 12.5 k/box

Parts Table

Part	Type differentiation	Ordering code	Remarks
BAS385	$V_R = 30\text{ V}$	BAS385-TR3 or BAS385-TR	Tape and Reel

Absolute Maximum Ratings

$T_{amb} = 25\text{ }^\circ\text{C}$, unless otherwise specified

Parameter	Test condition	Symbol	Value	Unit
Reverse voltage		V_R	30	V
Peak forward surge current	$t_p = 10\text{ ms}$	I_{FSM}	5	A
Repetitive peak forward current	$t_p \leq 1\text{ s}$	I_{FRM}	300	mA
Forward continuous current		I_F	200	mA
Average forward current	$V_{RWM} = 25\text{ V}$	I_{FAV}	200	mA

Thermal Characteristics

$T_{amb} = 25\text{ }^\circ\text{C}$, unless otherwise specified

Parameter	Test condition	Symbol	Value	Unit
Junction to ambient air	on PC board 50 mm x 50 mm x 1.6 mm	R_{thJA}	320	K/W
Junction temperature		T_j	125	$^\circ\text{C}$
Storage temperature range		T_{stg}	- 65 to + 150	$^\circ\text{C}$

Electrical Characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified

Parameter	Test condition	Symbol	Min.	Typ.	Max.	Unit
Forward voltage	$I_F = 0.1\text{ mA}$	V_F			240	mV
	$I_F = 1\text{ mA}$	V_F			320	mV
	$I_F = 10\text{ mA}$	V_F			400	mV
	$I_F = 30\text{ mA}$	V_F			500	mV
	$I_F = 100\text{ mA}$	V_F			800	mV
Reverse current	$V_R = 25\text{ V}$, $t_p = 300\text{ }\mu\text{s}$	I_R			2.3	μA
Diode capacitance	$V_R = 1\text{ V}$, $f = 1\text{ MHz}$	C_D			10	pF

Typical Characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified

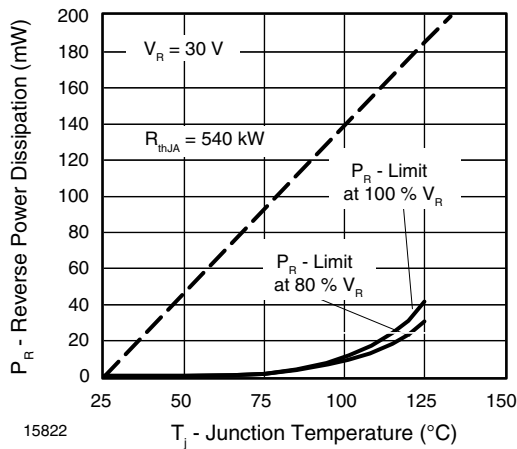


Figure 1. Max. Reverse Power Dissipation vs. Junction Temperature

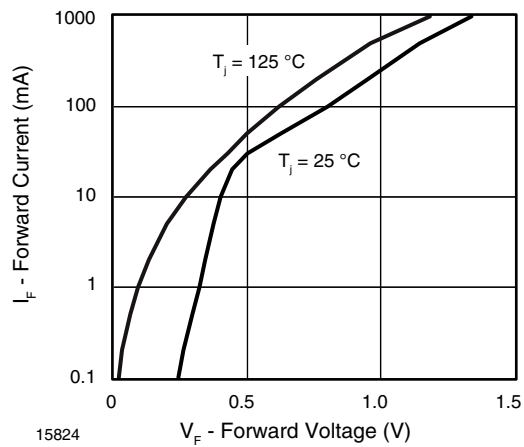


Figure 3. Forward Current vs. Forward Voltage

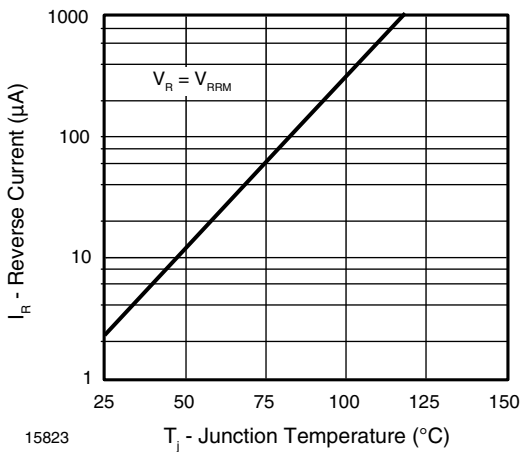


Figure 2. Reverse Current vs. Junction Temperature

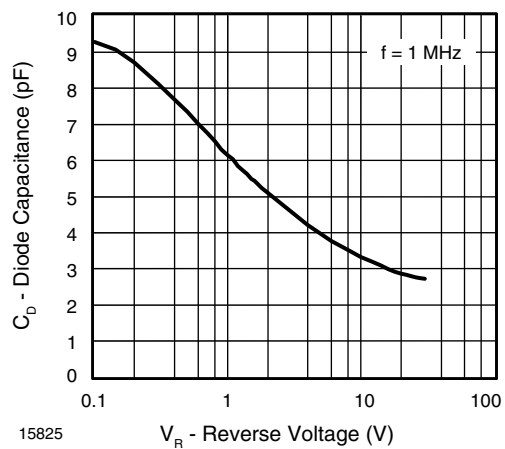


Figure 4. Diode Capacitance vs. Reverse Voltage

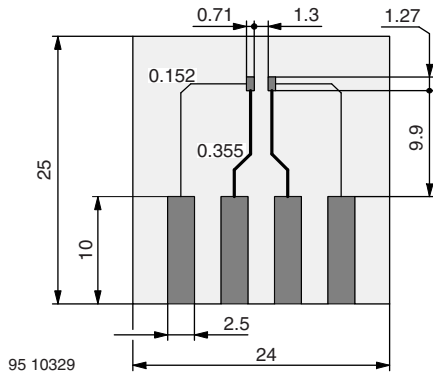
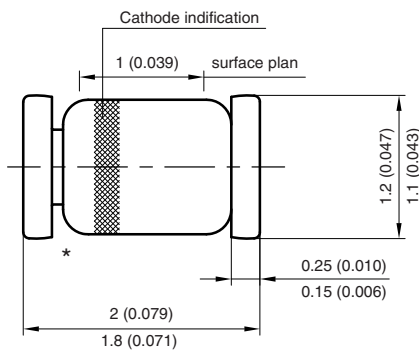
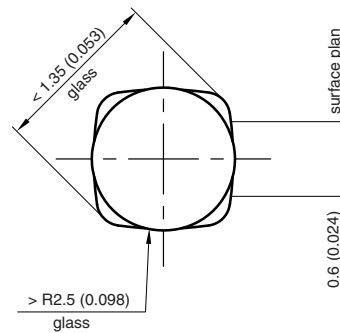


Figure 5. Board for R_{thJA} definition (in mm)

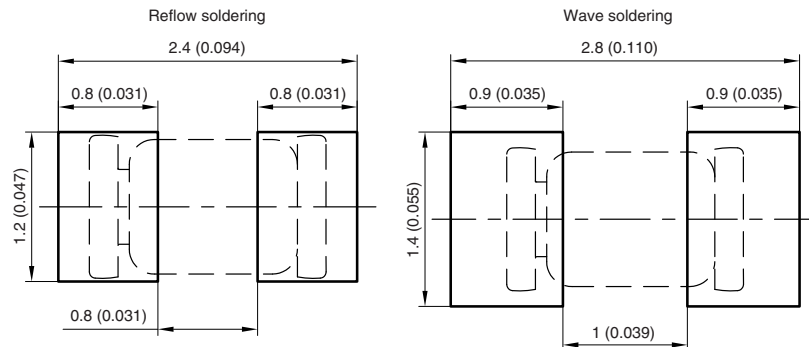
Package Dimensions in millimeters (inches): MicromELF



* The gap between plug and glass can be either on cathode or anode side



Foot print recommendation:



Created - Date: 26 July 1996
 Rev. 13 - Date: 07 June 2006
 Document no.: 6.560-5007.01-4
 96 12072



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